COMBINED DECLARATION AND POWER OF ATTORNEY FOR UTILITY PATENT APPLICATION

As a below-named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention titled:

				•	
Se	miconductor multipac	kage module including j	processor and memo	ry package as:	semblies
the spe	cification of which				
	is attached hereto.	was filed on	as Application No,		
	and was amen	ded on (<i>if applicable</i>).			
specific	<u>-</u>	I have reviewed and ι ms, as amended by any a			ove-identified
"Each i good fa that ind known patenta	tion in accordance with ndividual associated with hith in dealing with the C lividual to be material to to be material to pater	uty to disclose information Title 37, Code of Federal that the filling and prosecution of the filling and prosecution of the filling and prosecution of the filling as defined in a patent was cited by and 1.98."	Regulations, § 1.56(a) on of a patent application of a patent application to disclose to the O in this sectionThe dusatisfied if all informat	which states in on has a duty of the first all informants to disclose a lion known to be	relevant part: of candor and ition known to all information be material to
foreign	tion(s) for patent or in	priority benefits under T ventor's certificate as ind r inventor's certificate on claimed:	licated below and hav	e also identifie	ed below any
	Prior Foreign Application(s)			Priority Claimed	
		•		☐Yes	□No
	(Number) (Country)	(Day/Month/Year Filed)			
				☐ Yes	☐ No
	(Number) (Country)	(Day/Month/Year Filed)			
applicat disclose United Code o	tion(s), and under Titi tion(s), listed below and ed in the prior United S States Code, § 112, I a f Federal Regulations, {	enefit under Title 35, Ur le 35, United States Co , insofar as the subject m states application in the n acknowledge the duty to c § 1.56(a) which occurred al filing date of this applica	ide, § 119(e) of any latter of each of the cla manner provided by the disclose material inform between the filing date	United State lims of this app e first paragrap nation as define	s provisional dication is not oh of Title 35, ed in Title 37,
	60/460,541	04 April 2003	Pending		
	(Application No.)	Filing Date)	(Status: Patented, Po	ending, Abando	oned)
	(Application No.) (Filing Date) (Status: Patented, Pending, Abandoned				oned)
	(Application No.)	(Filing Date)	(Status: Patented, Pe	ending, Abando	oned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith, and to file, prosecute and to transact all business in connection with international applications directed to said invention:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18, United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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